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PATENT AND TRADEMARK OFFICE	6550-000013/COA	10/730,398
INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)	APPLICANT	
	Biehler, et al.	
Sheet 1 of 3	FILING DATE	GROUP
	12/8/2003	1742

U.S. PATENT DOCUMENTS

Ref. Desig.	Examiner's Initials	Document Number	Date	Name	Class/ Subclass	(If appropriate) Filing Date
1.		3,481,795*	12/1969	Lane		
2.		4,248,905*	12/1981	Harvey		
3.		4,358,884*	11/1982	Harvey et al.		
4.		4,506,822*	3/1985	Hammersand et al.		
5.		5,066,544*	11/1991	Betrabet et al.		
6.		5,094,700*	3/1992	Sekhar		
7.		5,344,607*	9/1994	Gonya et al.		
8.		5,429,689*	7/1995	Shangguan et al.		
9.		5,527,628*	6/1996	Anderson et al.		

* Previously submitted in an IDS in parent application.

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Ref. Desig.	Examiner's Initials	
1.		Anderson, et al., "Microstructural Modifications and Properties of Sn-Ag-Cu Solder Joints Induced By Alloying", Journal of Electronic Materials, vol. 31, no. 11, pp. 1166-1174 (2002)
2.		Attarwala, A.I. et al., "Confirmation of Creep and Fatigue Damage in Pb/Sn Solder Joints," J. Electron. Packag. 114:109-111 (1992)*
3.		Betrabet, H.S. et al., "Processing Dispersion-Strengthened Sn-Pb Solders To Achieve Microstructural Refinement And Stability," Script Metall. 25:2323-2328 (1991)*
4.		Betrabet, H.S. et al., "Towards Increased Fatigue Resistance In Sn-Pb Solders By Dispersion Strengthening," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1276-1277 (1992)*
5.		Clough, R.B. et al., "Preparation And Properties Of Reflowed Paste And Bulk Composite Solder," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1256-1265 (1992)*
6.		Frear, D.R. et al., "Thermal Fatigue In Solder Joints," JOM, pgs. 18-22 (June, 1988)*

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7.		Gibson, A.W. et al., "Issues Regarding Microstructural Coarsening Due To Aging Of Eutectic Tin-Silver Solder," Des. Reliab. Solders Solder Interconnect., Proc. Symp. (1997), 97-103*
8.		Ho, C.T. et al., "Carbon fiber reinforced tin-lead alloy as a low thermal expansion solder preform," *J. Mater. Res.* 5(6):1266-1270 (1990)*
9.		Jin, S., "Solder Materials Issues In High-Density Interconnection And Packaging," *Final Program ASM-TMS Materials Week '96*, ASM International and The Minerals, Metals & Materials Society, Cincinnati, Ohio, pp. 116 (1996)*
10.		Kuo, C.G. et al., "Fatigue Deformation Of In-Situ Composite Solders," 1st Int'l. Conf. Microstructures and Mechanical Properties of Aging Materials, ed. P.K. Liaw, R. Viswanathm, K.L. Murty, E.P. Simonen and D.R. Frear, The Minerals Metals & Materials Society, TMS, Warrendale, PA, pp. 417-423 (1993)*
11.		Kuo, C.G. et al., "Tensile And Creep Properties Of In-Situ Composite Solders," 1st Int'l. Conf. Microstructures and Mechanical Properties of Aging Materials, ed. P.K. Liaw, R. Viswanathm, K.L. Murty, E.P. Simonen and D.R. Frear, The Minerals Metals & Materials Society, TMS, Warrendale, PA, pp. 409-415 (1993)*
12.		Lau, J.H. et al., "Solder Joint Fatigue In Surface Mount Technology: State of the Art," Solid State Tech. pp. 91-104 (1985)*
13.		Lewis, R. (Ed.), Hawley's Condensed Chemical Dictionary, Thirteenth Ed., p. 483*
14.		Marshall, J.L. et al., "Composite Solders," IEEE Trans. Comp. Hybrids Manuf. Tech. 14(4):698-702 (1991)*
15.		Marshall, J.L. et al., "Microcharacterization Of Composite Solders," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1278-1283 (1992)*
16.		McCormack, M. et al., "Enhanced Solder Alloy Performance by Magnetic Dispersions," IEEE Trans. Comp. Hybrids Manuf. Tech.-Part A 17(3):452-457 (1994)*
17.		McCormack, M. et al., "The Design and Properties of New, Pb-Free Solder Alloys," Proc. IEEE/CPMT Int'l Electronics Manufacturing Technology Symp. pp. 7-14 (1994)*
18.		Miller, et al., "A Viable Tin-Lead Solder Substitute: Sn-Ag-Cu", Journal of Electronic Materials, vol. 23, no. 7, pp. 595-601 (1994).
19.		Moon, et al., "Experimental and Thermodynamic Assessment of Sn-Ag-Cu Solder Alloys", Journal of Electronic Materials, vol. 29, no.10, pp. 1122-1136 (2000)

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20.		Pinizzotto, R.F. et al., "Microstructural Development In Composite Solders Caused By Long Time, High Temperature Annealing," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1284-1298 (1992)*
21.		Sastry, S.M.L., et al., "Microstructures And Mechanical Properties Of In-Situ Composite Solders," Proc. Conf. NEPCON, West Anaheim, CA, pp. 1266-1275 (1992)*
22.		Shangguan, D. et al., "Evaluation of Lead-Free Eutectic Sn-Ag Solder For Automotive Electronics Packaging Applications," Proc. IEEE/CPMT Int'l Electronics Manufacturing Technology Symp., pp. 25-37 (1994)*
23.		Shine, M.C. et al., "Fatigue of Solder Joints in Surface Mount Devices," ASTM STP 942:588-610 (1988)*
24.		Smithells Metals Reference Book, 7th ed., Butterworth Heinemann, Oxford, 1992, p. 11-242, "Adapted Sn-Ag-Cu Phase Diagram"*
25.		Tien, J.K. et al., "Creep-Fatigue Interactions in Solders," IEEE Trans. Comp. Hybrids Manuf. Tech. 12(4):502-505 (1989)*
26.		Wasynczuk, J.A. et al., "Shear Creep Of Cu_6Sn_5/Sn-Pb Eutectic Composites," Proc. Conf. NEPCON., West Anaheim, CA, pp. 1245-1255 (1992)*
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